PRESS RELEASE

Palomar Technologies new 8100 Wire Bonder Increases Productivity and Efficiency

_Bonder offers new levels of productivity for operators and programmers_

Carlsbad, CA – Sept 29, 2020 – Palomar Technologies, a global leader in total process solutions for advanced photonics and microelectronic device packaging today announced the availability of their new Palomar 8100 Wire Bonder. The new 8100 wire bonder is a fully automated, thermosonic high-speed ball-and-stitch wire bonder capable of ball bumping and customized looping profiles. Based on Palomar’s proven wire bonder design, the Palomar 8100 incorporates the latest productivity technology and operator ergonomics.

“The new Palomar 8100 Wire Bonder builds upon the proven engineering of the Palomar 8000, while adding the latest technology in motion control, software and user experience. Transferring and maintaining programs across multiple systems is straightforward and requires no extra effort whether the systems are all 8100s or a mix of 8000s and 8100s,” said Rich Hueners, Vice President of Sales and Marketing for Palomar Technologies. “The Palomar 8000 Wire Bonder has had a successful 17-year run with a global installed base of more than $100M. It is the ball bonder of choice for Tier 1 companies who require high reliability, first-level interconnect in their advanced microelectronic packages. With new features such as Vision Standardization™, customers will find that moving from the 8000 to 8100 will be a seamless transition.”

The Palomar 8100 is ideal for a flexible range of applications by providing new methods for higher quality and reliability. It offers optimum performance for applications with tight spaces, fragile surfaces, flip-chip, deep access cavities and provides excellent material flexibility. Typical applications for the Palomar 8100 Wire Bonder include:

- Large complex hybrids
- HB/HP LED arrays
- Optoelectronic packaging
- Chip-on-board (COB)
- System in packages (SiPs)
- Specialty lead frames
- Automotive assemblies
- Flex circuits
- Multi-chip modules (MCMs)
- Fine pitch devices
- LEDs with running stitch

In addition to utilizing Palomar’s VisionPilot® Pattern Referencing software for vision processing, programmers can improve yield and utilization by using Bond Data Miner. This Palomar proprietary software provides traceability of bond parameters and a clear overview of processes and performance. Additionally, it includes Vision Standardization™, Palomar’s new software that calibrates images between...
different Palomar bonding systems, dramatically eliminating the time and cost associated with maintaining programs across multiple systems and numerous programs on a system over time. The Palomar 8100 is loaded with a full range of ergonomic features designed to increase operator efficiency and decrease fatigue, including:

- An optimized wire-feed path for faster loading and full view of the wire during operation
- All user interaction points comfortably within operator reach
- Adjustable, articulating monitors and keyboard to cater to all operators, either sitting or standing
- Microscope available for use while the bonder is in operation
- Graphical real-time displays of all vital operations and gauges in one location
- Rapid, informed response by employing simple color-coded error signals for all situations

The Palomar 8100 wire bonder will be the focus of Palomar’s exhibit at iMAPS Virtual Exhibition from October 5 – 8th. For more information on the Palomar 8100 Wire Bonder, visit: https://www.palomartechnologies.com/product/8100-wire-bonder or register for Palomar’s webinar: Taking Wire Bonding to New Levels of Efficiency and Productivity - Palomar 8100 Wire Bonder scheduled for October 21, 2020.

Media Contact:
Rebecca Janzon
Director of Marketing Communications
Email: rjanzon@bonders.com
Mobile: 760-409-7453

About Palomar Technologies
Palomar Technologies makes the connected world possible by delivering a Total Process Solution™ for advanced photonic and microelectronic device assembly processes utilized in today’s smart, connected devices. With a focus on flexibility, speed and accuracy, Palomar’s Total Process Solution includes Palomar die bonders, Palomar wire and wedge bonders, SST vacuum reflow systems, along with Innovation Centers for outsourced manufacturing and assembly, and Customer Support services, that together deliver improved production quality and yield, reduced assembly times, and rapid ROI.

With its deep industry expertise, Palomar equips customers to become leaders in the development of complex, digital technologies that are the foundation of the connected world and the transmission of data generated by billions of connected devices. Palomar solutions are utilized by the world’s leading companies providing solutions for Datacom, 5G, electric vehicle power modules, autonomous vehicles/LiDAR, enhanced mobile broadband, Internet of Things, SMART technology, and mission critical services.

Headquartered in Carlsbad, California, Palomar offers global sales, service and application support from its offices in the USA, Germany, Singapore and China. For more information, visit: http://www.palomartechnologies.com